



IC Packages, Assembly & Prototype Services

Press Release

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Quik-Pak Announces Wafer Backgrinding Services

SAN DIEGO, August 21, 2007-- Quik-Pak, a division of Delphon Industries and leader in quick-turn integrated circuit (IC) packaging, assembly and service, has announced the installation of a new Disco Automatic Surface Grinding system. This equipment provides in-house capability to grind wafers up to 200mm in diameter down to a thickness of 150µm (6 mils), supporting the latest package technology and stacked die applications. This newest capital acquisition, along with a Royce Pick & Place system, scheduled for September installation, complements the existing Disco Automatic Wafer Dicing Saw and allows Quik-Pak to deliver complete wafer preparation services. Quik-Pak is also the world's largest supplier of open cavity plastic packages, that give IC designers the option to insert

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new die in existing production packages for design verification, testing and customer samples.

The new backgrinding service can be utilized either as part of Quik-Pak's full turnkey packaging and assembly process or combined with wafer dicing and pick & place to provide complete wafer preparation services to customers with internal assembly capabilities.

For further information, contact Quik-Pak, 10987 Via Frontera, San Diego, CA 92127, phone 1(858)674-4676, moreinfo@icproto.com.

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